

Title (en)
PLATING BATH COMPOSITION FOR ELECTROLESS PLATING OF GOLD

Title (de)
GALVANISIERUNGSBADZUSAMMENSETZUNG ZUR STROMLOSEN GALVANISIERUNG VON GOLD

Title (fr)
COMPOSITION DE BAIN DE PLACAGE POUR UN DÉPÔT AUTOCATALYTIQUE D'OR

Publication
EP 3144413 B1 20180425 (EN)

Application
EP 15186095 A 20150921

Priority
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Abstract (en)
[origin: EP3144413A1] An electroless aqueous gold plating bath, comprising at least one source of gold ions and at least one reducing agent for gold ions, characterized in that it comprises at least one ethylenediamine derivative according to formula (I) wherein the residues R 1 and R 2 comprise 2 to 12 carbon atoms and are selected from the group consisting of branched alkyl, unbranched alkyl, cycloalkyl or combinations thereof wherein the individual residues R 1 and R 2 are the same or different as plating enhancer compound. The electroless aqueous gold plating bath is suitable to provide soft gold layers useful for wire bonding and soldering applications which are required for electronic components.

IPC 8 full level
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CPC (source: CN EP KR US)
C23C 18/1637 (2013.01 - CN); **C23C 18/1844** (2013.01 - CN EP KR); **C23C 18/44** (2013.01 - CN EP KR US)

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